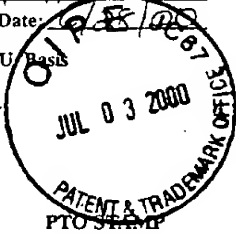#9A

Serial No. 09/198,849 Filing Date 11/24/98 OFGS File No. P/1929-47

Title DEVICE MOUNTING METHOD

First Inventor Yoshinobu Kaneyama Date 6/27/00

The PTO has received: Last Due Date 6/28/00

☐ Patent Application of_____
  Pages (including claims & abstract)
  ☐ Declaration or ☐ Designation Sheet
☐ Drawings_____ Sheet(s)/Figs._____ to_____
☐ Priority Document
☐ Small Entity Declaration
☐ Assignment & Conveyance Cover Sheet
☐ Information Disclosure Statement
☐ PTO-1449
☒ Amendment + Transmittal
☐ Affidavit or Declaration
☐ _____
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☐ TM Application ☐ ITU Basis
☐ Statement of Use
☐ Extension of Time
☐ Notice of Appeal
☐ Brief
☐ Petition
☐ Status Request
☐ Issue Fee
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Yoshinobu KANEYAMA

Serial No.: 09/198,849

Filed: November 24, 1998

For: DEVICE MOUNTING METHOD

New York, New York

Date: June 27, 2000

Group Art Unit: 1725

Examiner: M. Elve

Asst. Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Office Action mailed March 28, 2000, please reconsider the above-identified application amended as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1.   (Amended) A [mount] mounting method for joining a device to a substrate using solder [with soldering], characterized in that [joint] the joining of said device and said substrate [through solder] is performed while said device is at least partially submerged in a liquid, wherein said device is at least partially supported by a buoyant force.

2.   (Amended) The [mount] mounting method as claimed in claim 1, wherein the [joint based on] joining of said substrate to said device using said solder is performed while [ultrasonic] a vibration is applied to said [solder through the liquid] device.

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